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A

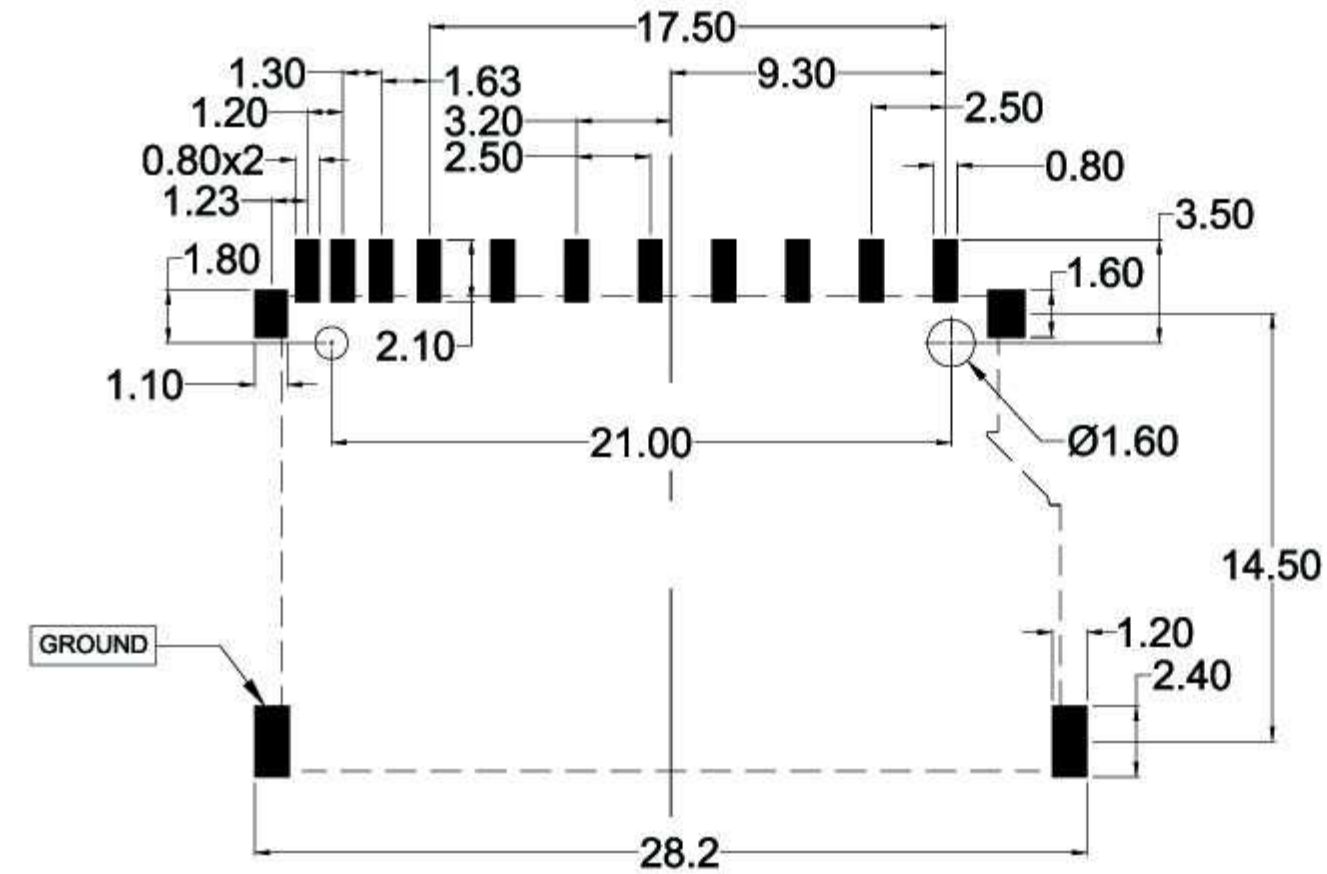
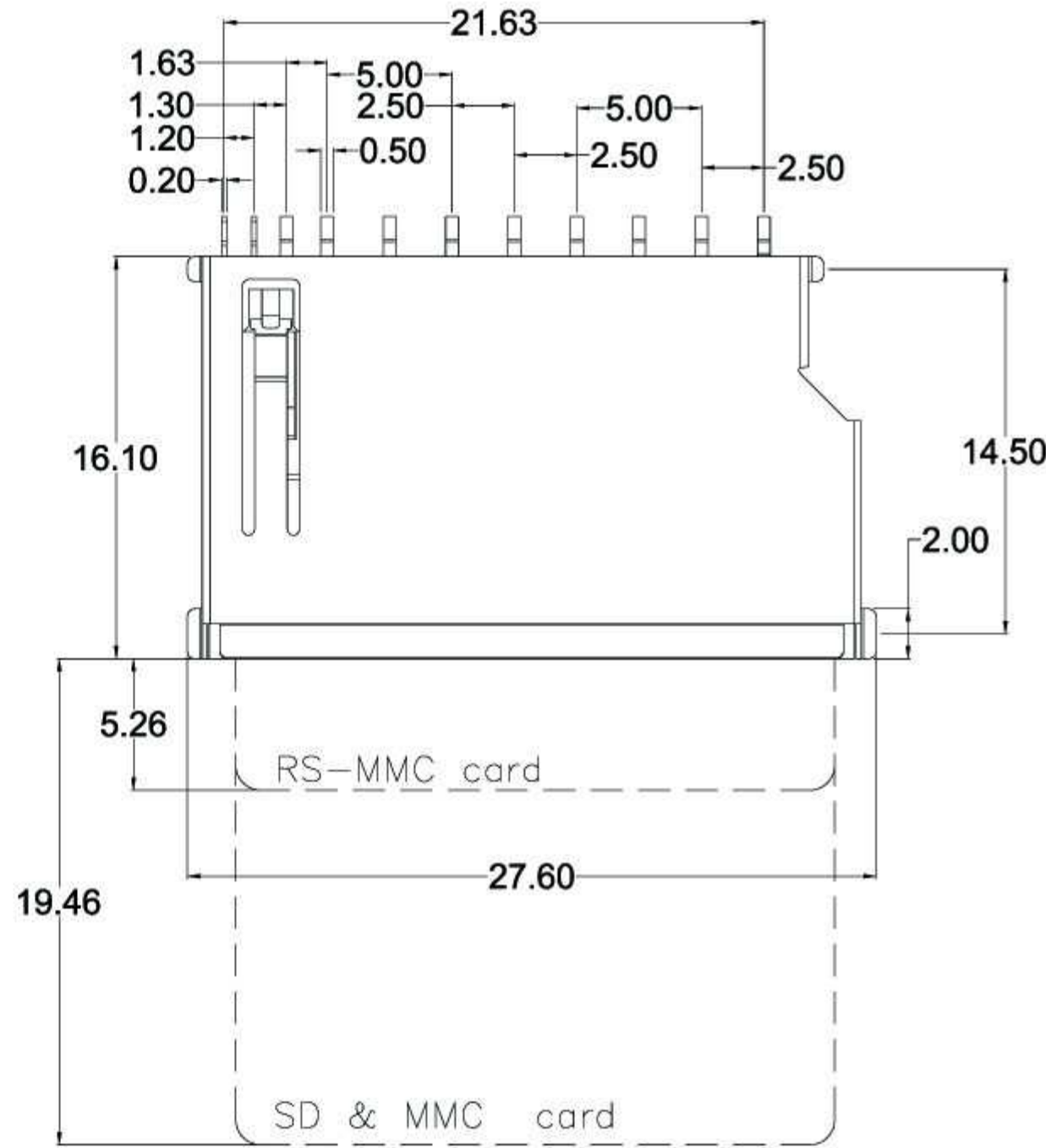
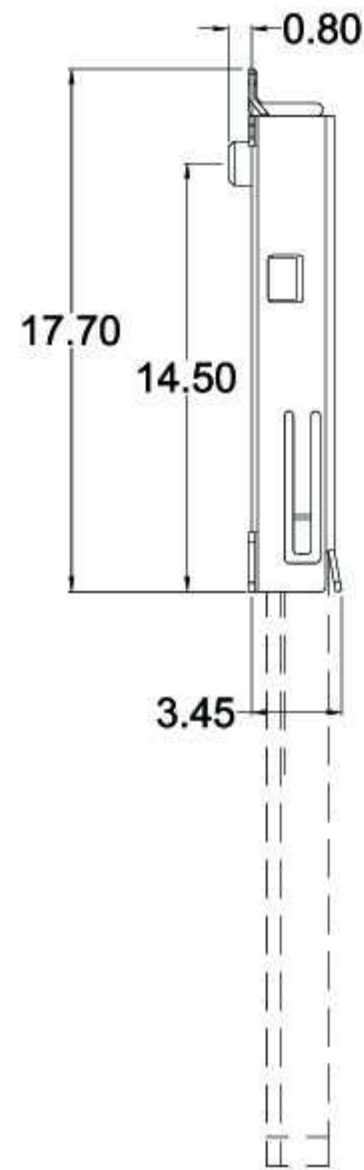
B

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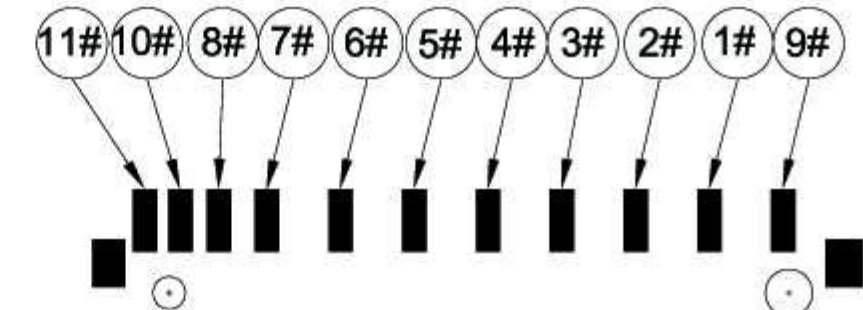
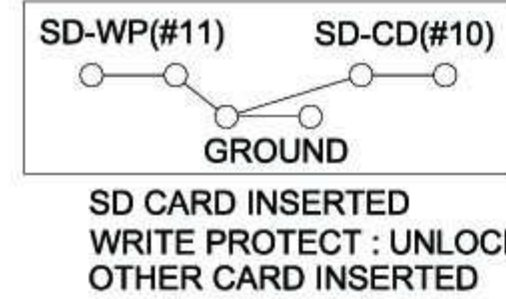
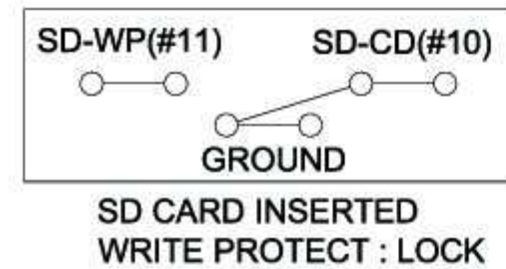
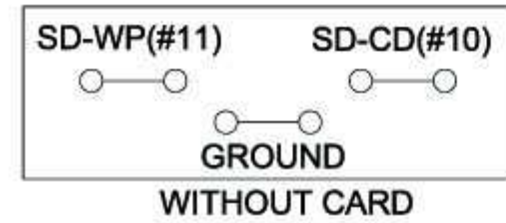
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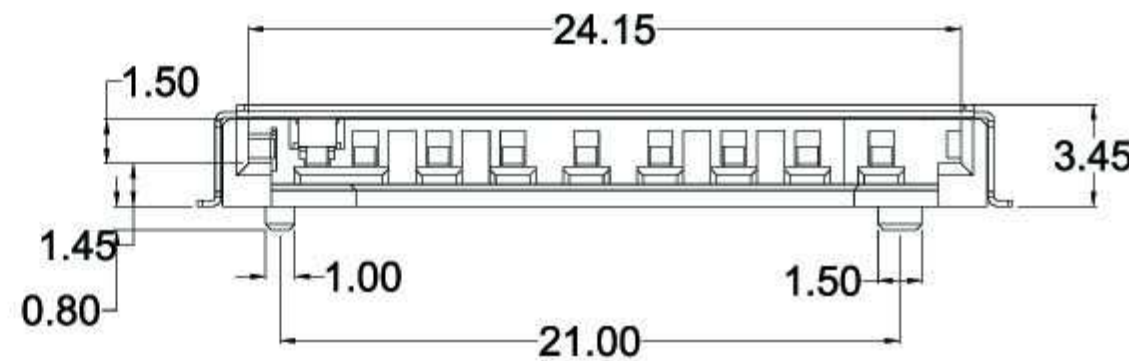
PCB LAYOUT



PIN DESIGN:

PIN NO.	PIN DEFINITION	MEMORY CARD PIN NO.
1#	RSV / DAT3	MMC&RS-MMC&SD
2#	CMD	MMC&RS-MMC&SD
3#	GND	MMC&RS-MMC&SD
4#	VCC	MMC&RS-MMC&SD
5#	CLK	MMC&RS-MMC&SD
6#	GND	MMC&RS-MMC&SD
7#	DAT 0	MMC&RS-MMC&SD
8#	DAT 1	SD
9#	DAT 2	SD
10#	CD	SD
11#	WP	SD

NOTES:  
 1.MATERIAL  
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC.  
 CONTACT: COPPER ALLOY.  
 SHELL: COPPER ALLOY.  
 2.PLATING  
 CONTACT AREA: GOLD PLATED OVER Ni.  
 SOLDER TAIL: 100 u" MIN Sn/Pb PLATED OVER Ni.  
 SHELL SOLDER AREA: GOLD PLATED OVER Ni.  
 3.RATING  
 CURRENT RATING: 0.5A AC/DC  
 VOLTAGE RATING: 250VRMS  
 OPERATING TEMPERATURE:-25 °C~90°C  
 4.SPECIFICATION  
 CONTACT RESISTANCE: 40 MillioHMS  
 DIELECTRIC WITHSTANDING VOLTAGE: 500VAC MegOHMS  
 INSULATION RESISTANCE: 100 MegOHMS  
 INSERTION FORCE: 40N MAX.  
 SEPARATION FORCE: 2N MIN.



UNLESS OTHERWISE SPECIFIED TOLERANCE TO BE		REV.		CHANGE DETAILS		BY	DATE	CHG/No
LINEAR	ANGULAR							
X ±	FIRST	X' ±	FIRST					
XX ±	SND	X'X' ±	SND					
XX ±	THIRD	X'X'X' ±	THIRD					
CAD FILE:		DRN:	AARON	DATE:	05/03/18	TITLE:		
BREAK ALL SHARP EDGES AND REMOVE ALL BURRS		MATL:	CKD:	PHILIP	DATE:	05/03/20	SD + MMC + RS-MMC	
DO NOT SCALE		FINISH:	APP'D:	BILL	DATE:	05/03/20	3 IN 1 Card Connector	
DIMENSIONS IN MILLIMETRES		SCALE: 5:1 UOS		PART No.:	SD-S01	SIZE:	A4	SHEET 1 / 1
		THIRD ANGLE PROJECTION						

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